

Appl. No. 10/650,504
Amdt. Dated March 15, 2007
Reply to Office Action of December 15, 2006

Attorney Docket No. 81872.0052
Customer No. 26021

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-12. (Canceled)

13. (Currently amended): A ~~dry etching~~ method for producing a solar cell, etching a surface of a substrate to be etched, said method comprising:

placing a substrate ~~for a solar cell to be etched~~ on an electrode inside a chamber; ~~wherein a part of said chamber is connected to a ground~~; and

covering said substrate to be etched with a plate between ~~said part of said chamber and said electrode~~, wherein said plate is provided with a number of opening portions; and [.,.]

forming textures on a surface of the substrate by using residues being chiefly composed of components of the substrate as an etching mask, wherein a distance between ~~said substrate and a surface of said plate~~ opposing said substrate to be etched and said substrate to be etched in a peripheral portion of said plate is set shorter than a distance between ~~said substrate and said surface opposing said substrate to be etched and said substrate to be etched~~ in a central portion of said plate.

14. (Currently amended): The ~~dry etching~~ method for producing a solar cell according to claim 13, wherein said textures are formed by dry etching method is a reactive ion etching method.

15-19. (Canceled)

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20. (Currently amended): A ~~dry etching method for producing a solar cell,~~ etching a surface of a substrate to be etched, said method comprising:

placing a substrate ~~for a solar cell~~ to be etched on an electrode inside a chamber; wherein a part of said chamber is connected to a ground;

covering said substrate to be etched with a plate provided with a number of opening portions; and

forming fine textures on a surface of said substrate to be etched ~~using residues being chiefly composed of components of the substrate as an etching mask, by applying RF power to said electrode,~~

wherein ~~said plate is provided with a protruding wall is provided to said plate~~ on a surface opposing said substrate to be etched and said protruding wall is separated from a nearest surface of said substrate by a space.

21. (Original): The ~~dry etching method for producing a solar cell~~ according to claim 20, wherein ~~said textures are formed by dry etching method~~ is a reactive ion etching method.

22-23. (Canceled)

24. (New): The method for producing a solar cell according to Claim 13, wherein said plate is provided with a protruding wall on a surface thereof opposing said substrate and said protruding wall is separated from a nearest surface thereof opposing said substrate and said protruding wall is separated from a nearest surface of said substrate by a space.

25. (New): The method for producing a solar cell according to Claim 20, wherein a lower end portion of said protruding wall abuts on said electrode.

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26. (New): The method for producing a solar cell according to Claim 20,
wherein the substrate for a solar cell is a silicon substrate.